

Product specification – Sep 16, 2004 V.2



Innovative Service Around the Globe

DATA SHEET

RC2010 (Pb Free) 5%, 1%

**GENERAL PURPOSE CHIP RESISTORS** 

# Phicomp

#### <u>SCOPE</u>

This specification describes RC2010 series chip resistors with lead-free terminations made by thick film process.

#### ORDERING INFORMATION

Part number is identified by the series, size, tolerance, packing type, temperature coefficient, taping reel and resistance value.

#### PHYCOMP ORDERING CODE

VVV VVVVV I

# 12NC CODE

$\frac{1}{2}$			
(I)	(2	2) (3) (4)	
TYPE/ START	TOL.	RESISTANCE	EMBOSSED TAPE ON REEL (units) <sup>(2)</sup>
2010 IN <sup>(1)</sup>	(%)	RANGE	4,000
PRCI II 2322	±5%	I to 22 M $\Omega$	760 60xxx
PRCI II 2322	±1%	I to 10 $\text{M}\Omega$	761 6xxxx
Jumper 2322	-	0 Ω	760 90003

- The resistors have a 12-digit ordering code starting with 2322.
- (2) The subsequent 4 or 5 digits indicate the resistor tolerance and packaging.
- (3) The remaining 4 or 3 digits represent the resistance value with the last digit indicating the multiplier as shown in the table of "Last digit of 12NC".
- (4) "L" means lead-free terminations.

#### **ORDERING EXAMPLE**

The ordering code of a PRCIII resistor, value 56  $\Omega$  with ±1% tolerance, supplied in tape of 4,000 units per reel is: 232276165609L.

Last digit of I2NC					
Resistance	decade <sup>(3</sup>	Last digit			
0.01 to 0.0	976 Ω		0		
0.1 to 0.97	6Ω	7			
l to 9.76 🤇	2	8			
10 to 97.6	Ω	9			
100 to 976	1				
l to 9.76 k	2				
10 to 97.6	3				
100 to 976 kΩ			4		
l to 9.76 MΩ			5		
10 to 97.6 MΩ			6		
Example:	0.02 Ω	=	0200 or 200		
	0.3 Ω	=	3007 or 307		
	ΙΩ	=	1008 or 108		
	33 kΩ	=	3303 or 333		
	10 MΩ	=	1006 or 106		

#### CTC CODE

RC2010	<u>x</u>	<u>x</u>	<u>x</u>	<u>xx</u>	<u>xxxx</u>	L
	(I)	(2)	(3)	(4)	(5)	(6)

### (I) TOLERANCE

 $F = \pm 1\%$ 

 $J = \pm 5\%$ 

#### (2) PACKAGING TYPE

K = Embossed taping reel

#### (3) TEMPERATURE COEFFICIENT OF RESISTANCE

– = Base on spec

#### (4) TAPING REEL

07 = 7 inch dia. Reel

(5) RESISTANCE VALUE

5R6, 56R, 560R, 5K6, 56K, 22M.

#### (6) RESISTOR TERMINATIONS

L = Lead free terminations (pure Tin)

#### **ORDERING EXAMPLE**

The ordering code of a RC2010 chip resistor, value 56  $\Omega$  with ±1% tolerance, supplied in 7-inch tape reel is: RC2010FK-0756RL.

#### NOTE

- 1. The "L" at the end of the code is only for ordering. On the reel label, the standard CTC or 12NC will be mentioned an additional stamp "LFP"= lead free production.
- 2. Products with lead in terminations fulfil the same requirements as mentioned in this datasheet.
- 3. Products with lead in terminations will be phased out in the coming months (before July 1st, 2006)



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# MARKING

 RC2010
 E-24 series: 3 digits

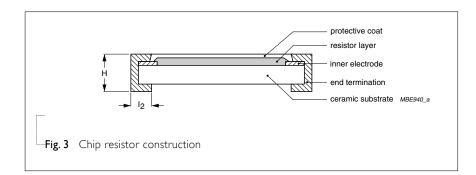
 Fig. 1
 Value=10 KΩ

 Fig. 2
 Value=10 KΩ

For marking codes, please see EIA-marking code rules in data sheet "Chip resistors instruction".

## **CONSTRUCTION**

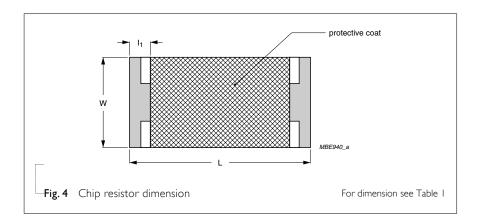
The resistors are constructed out of a high-grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive paste. The composition of the paste is adjusted to give the approximate required resistance and laser cutting of this resistive layer that achieves tolerance trims the value. The resistive layer is covered with a protective coat and printed with the



resistance value. Finally, the two external terminations (pure Tin) are added. See fig. 3.

#### **DIMENSIONS**

Table I	
TYPE	RC2010
L (mm)	5.00 ±0.10
W (mm)	2.50 ±0.15
H (mm)	0.55 ±0.10
l <sub>l</sub> (mm)	0.45 ±0.15
l <sub>2</sub> (mm)	0.50 ±0.20





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### ELECTRICAL CHARACTERISTICS

Table 2		
CHARACTERISTICS	F	RC2010 3/4 W
Operating Temperature Range	-55	°C to +155 °C
Maximum Working Voltage		200 V
Maximum Overload Voltage		500 V
Dielectric Withstanding Voltage		500 V
	5% (E24)	I $\Omega$ to 22 M $\Omega$
Resistance Range	1% (E96)	I $\Omega$ to I0 M $\Omega$
	Zero Ohm Ju	$mper < 0.05 \Omega$
Temperature Coefficient	$10 \Omega < R \le 10 M\Omega$	±100 ppm/°C
Temperature Coencient	$R \le 10 \Omega; R > 10 M\Omega$	±200 ppm/°C
Jumper Criteria	Rated Current	2.0 A
Jumper Criteria	Maximum Current	10.0 A

# FOOTPRINT AND SOLDERING PROFILES

For recommended footprint and soldering profiles, please see the special data sheet "Chip resistors mounting".

# ENVIRONMENTAL DATA

For material declaration information (IMDS-data) of the products, please see the separated info "Environmental data".

## PACKING STYLE AND PACKAGING QUANTITY

**Table 3** Packing style and packaging quantity

PRODUCT TYPE	PACKING STYLE	REEL DIMENSION	QUANTITY PER REEL
RC2010	Embossed taping reel (K)	7" (178 mm)	4,000 units

## NOTE

I. For embossed tape and reel specification/dimensions, please see the special data sheet "Packing" document.

#### FUNCTIONAL DESCRIPTION

#### **POWER RATING**

RC2010 rated power at 70°C is 3/4 W

### **RATED VOLTAGE**

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

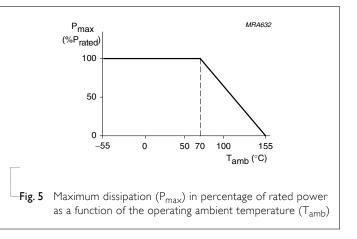
 $V=\sqrt{(P X R)}$ 

Where

V=Continuous rated DC or AC (rms) working voltage (V)

P=Rated power (W)

R=Resistance value ( $\Omega$ )





# TESTS AND REQUIREMENTS

Table 4 Test condition, procedure and requirements

FEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Temperature	MIL-STD-202F-method 304;	At +25/–55 °C and +25/+125 °C	Refer to table 2
Coefficient of Resistance	JIS C 5202-4.8	Formula:	
(T.C.R.)			
, , , , , , , , , , , , , , , , , , ,		T.C.R= $\frac{R_2-R_1}{R_1(t_2-t_1)} \times 10^6 \text{ (ppm/°C)}$	
		Where t <sub>1</sub> =+25 °C or specified room temperature	
		$t_2$ =–55 °C or +125 °C test temperature	
		$R_1$ =resistance at reference temperature in ohms	
		$R_2$ =resistance at test temperature in ohms	
Thermal Shock	MIL-STD-202F-method 107G;	At -65 (+0/-10) °C for 2 minutes and at +155	±(0.5%+0.05 Ω) for 1% tol.
	IEC 60115-1 4.19	(+10/–0) °C for 2 minutes; 25 cycles	$\pm$ (1.0%+0.05 $\Omega$ ) for 5% tol.
Low	MIL-R-55342D-Para 4.7.4	At –65 (+0/–5) °C for I hour; RCVV applied	±(0.5%+0.05 Ω) for 1% tol
Temperature		for 45 (+5/–0) minutes	±(1.0%+0.05 Ω) for 5% tol.
Operation			No visible damage
Short Time	MIL-R-55342D-Para 4.7.5;	2.5 × RCWV applied for 5 seconds at room	±(1.0%+0.05 Ω) for 1% tol.
Overload	IEC 60115-1 4.13	temperature	±(2.0%+0.05 Ω) for 5% tol.
			No visible damage
Insulation	MIL-STD-202F-method 302;	RCOV for 1 minute	≥10 GΩ
Resistance	IEC 60115-1 4.6.1.1	Type RC2010	
		<b>Voltage (DC)</b> 500 ∨	
Dielectric	MIL-STD-202F-method 301;	Maximum voltage (V <sub>rms</sub> ) applied for 1 minute	No breakdown or flashover
Withstand	IEC 60115-1 4.6.1.1	Type RC2010	
Voltage		Voltage (AC) 500 V <sub>rms</sub>	
Resistance to	MIL-STD-202F-method 210C;	Unmounted chips; 260 $\pm$ 5 °C for 10 $\pm$ 1	±(0.5%+0.05 Ω) for 1% tol.
Soldering	IEC 60115-1 4.18	seconds	$\pm$ (1.0%+0.05 $\Omega$ ) for 5% tol.
Heat	··· · · · ·		No visible damage
Life	MIL-STD-202F-method 108A;	At 70±2 °C for 1,000 hours; RCWV applied for	±(1%+0.05 Ω) for 1% tol.
	IEC 60115-1 4.25.1	1.5 hours on and 0.5 hour off	$\pm$ (3%+0.05 Ω) for 5% tol.

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TEST METHOD

TEST

Chip Resistor Surface Mount RC SERIES 2010 (Pb Free)

PROCEDURE

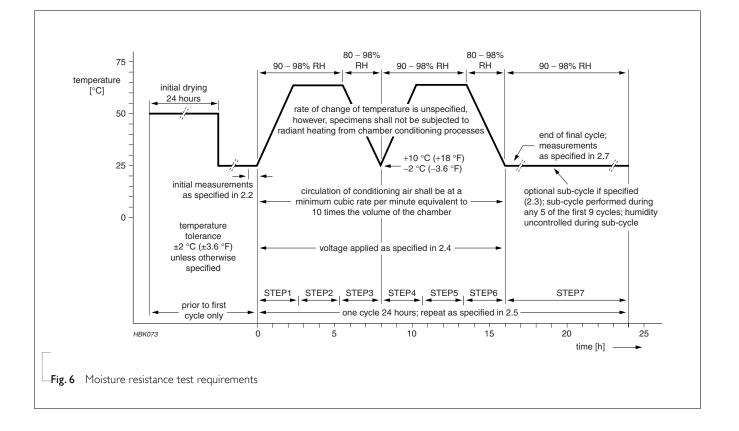
 $\frac{\text{Product specification}}{6}$ 

REQUIREMENTS

51	TEGTTIETTIGE		•	
Solderability	MIL-STD-202F-method 208A;	Solder bath at 245±3 °C	Well tinned (≥95% cove	ered)
	IEC 60115-1 4.17	Dipping time: 2±0.5 seconds	No visible damage	
Bending	JIS C 5202.6.14;	Resistors mounted on a 90 mm glass epoxy	±(1.0%+0.05 Ω) for 1%	á tol.
Strength	IEC 60115-1 4.15	resin PCB (FR4)	$\pm$ (1.0%+0.05 $\Omega$ ) for 5%	s tol.
		Bending: 2 mm	No visible damage	
Resistance to	MIL-STD-202F-method 215;	lsopropylalcohol (C <sub>3</sub> H <sub>7</sub> OH) or dichloromethane	No smeared	
Solvent	IEC 60115-1 4.29	$(CH_2CI_2)$ followed by brushing		
Noise	JIS C 5202 5.9;	Maximum voltage (V <sub>rms</sub> ) applied.	Resistors range	Value
	IEC 60115-1 4.12		R < 100 Ω	10 dE
			$ 00 \ \Omega \le R <   K\Omega$	24 dE
			$  K\Omega \le R <  0 K\Omega$	34 dE
			$10 \text{ K}\Omega \leq \text{R} < 100 \text{ K}\Omega$	44 dE
			$100 \text{ K}\Omega \leq \text{R} < 1 \text{ M}\Omega$	46 dE
			$  M\Omega \le R \le 22 M\Omega$	48 dE
Humidity	JIS C 5202 7.5;	1,000 hours; 40±2 °C; 93(+2/–3)% RH	±(0.5%+0.05 Ω) for 1%	s tol.
(steady state) IEC 60115-8 4.24.8		RCWV applied for 1.5 hours on and 0.5 hour off		
Leaching	EIA/IS 4. I 3B;	Solder bath at 260±5 °C	No visible damage	
Leaching	EIA/IS 4.13B; IEC 60115-8 4.18	Solder bath at 260±5 °C Dipping time: 30±1 seconds	No visible damage	
Intermittent		Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for	No visible damage $\pm (1.0\% \pm 0.05 \Omega)$ for 1%	ő tol.
	IEC 60115-8 4.18	Dipping time: 30±1 seconds		
Intermittent	IEC 60115-8 4.18	Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000	±(1.0%+0.05 Ω) for 1%	
Intermittent Overload Resistance to Vibration Moisture	IEC 60115-84.18 JIS C 5202 5.8	Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000 cycles	±(1.0%+0.05 Ω) for 1%	ó tol.
Intermittent Overload Resistance to Vibration	IEC 60115-8 4.18 JIS C 5202 5.8 On request	Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000 cycles On request	±(1.0%+0.05 Ω) for 1% ±(2.0%+0.05 Ω) for 5%	s tol.



Chip Resistor Surface Mount RC SERIES 2010 (Pb Free)





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# <u>REVISION HISTORY</u>

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 2	Sep 16, 2004	-	- New datasheet for 2010 thick film 1% and 5% with lead-free terminations
			- Replace the 2010 part of pdf files: PRC111_1_5, PRC111_5_6
			- Test method and procedure updated

